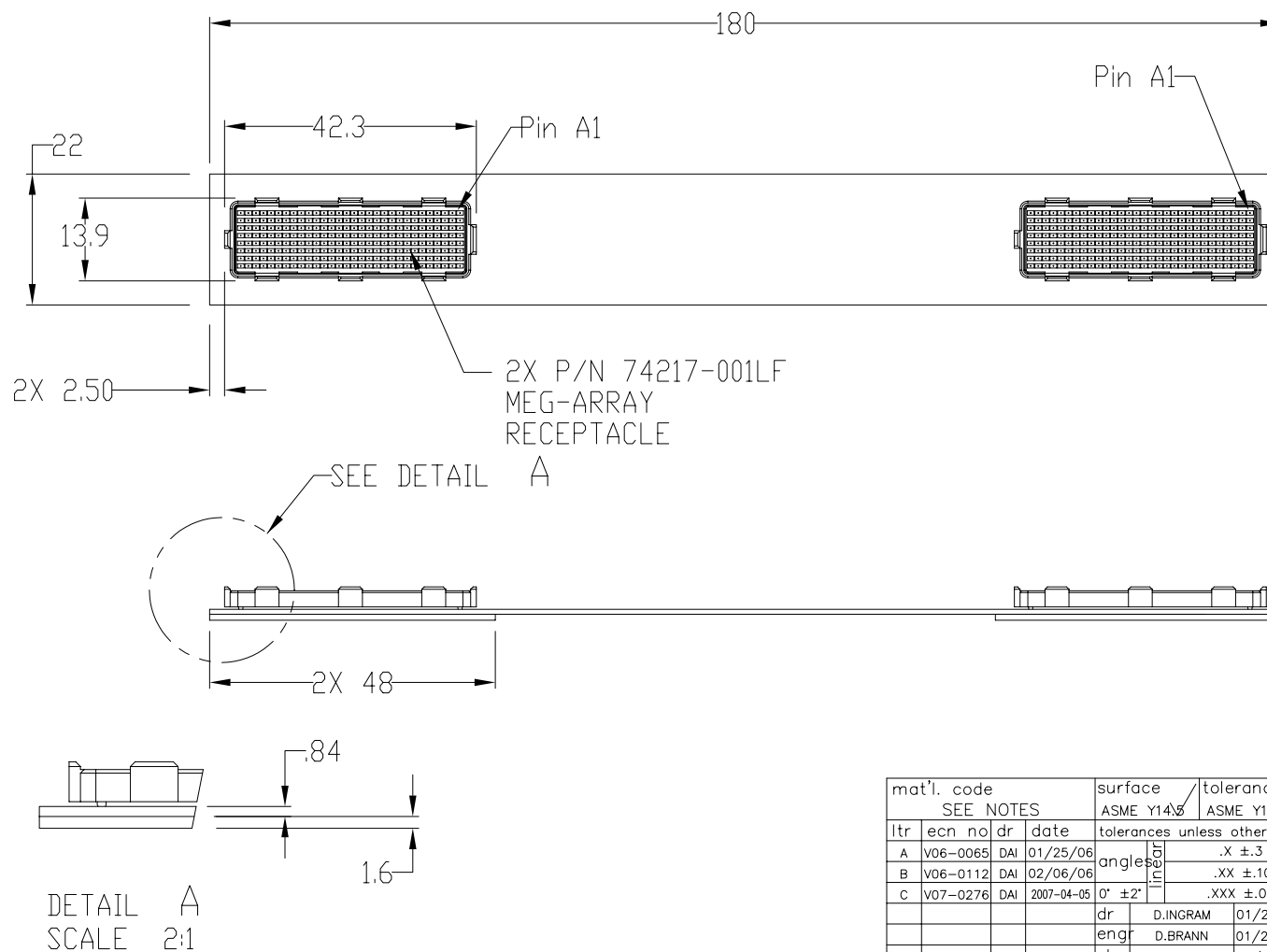


PRODUCT NUMBER

10061262-001LF



mat'l. code				surface		tolerance	projection	product family	
SEE NOTES				ASME Y14.5		ASME Y14.5	specified	title	
ltr	ecr	no	dr	date	tolerances unless otherwise				
A	V06-0065	DAI	01/25/06		angle 5°		.X ±.3		
B	V06-0112	DAI	02/06/06		0° ±2'		.XX ±.10		
C	V07-0276	DAI	2007-04-05				.XXX ±.050		
					dr	D.INGRAM	01/25/06		
					engr	D.BRANN	01/25/06		
					chr	D.BRANN	01/25/06		
					appd	D.BRANN	01/25/06		
sheet	revision	c	c						
index	sheet	1	2						



scale 1:1

MM

product family

title

FLEX CIRCUIT W/240 POS. MEG-ARRAY  
RECEPTACLE ASSEMBLIES

dwg no

10061262

sheet 1 of 2

size

A4

type

CUSTOMER Drawing

PRODUCT NUMBER

10061262-001LF

## NOTES:

## 1. MATERIAL:

HOUSING: LCP

CONTACT: COPPER ALLOY

CONTACT PLATING: 38 $\mu$ m (15 $\mu$  in) Au OVER Ni

SOLDER BALL PLATING: SnAgCu

BACKER BOARD: G-10

FLEX CIRCUIT: Polyimide

2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE  
DUE TO REFLOW ATTACHEMENT.

3. LEAD FREE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND  
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

4. FOR PROPER APPLICATION, FOLLOW FCI APPLICATION  
SPECIFICATION GS-20-033.

5. CONSTRUCTION PER IPC-6013 CLASS II TYPE 3 OR 4.

6. MEG-ARRAY PRODUCT SPECIFICATION: GS-12-100.

Cover coat

 $\frac{1}{2}$  OZ Copper

Adhesive

Polyimide

.81/.84

mat'l. code				surface	tolerance	projection	product family		
SEE NOTES				ASME Y14.5	ASME Y14.5		title		
ltr	ec	no	dr	date	tolerances unless otherwise specified		FLEX CIRCUIT W/240 POS. MEG-ARRAY		
c					angle	MM	RECEPTACLE ASSEMBLIES		
					0° ±2'	scale 1:1	dwg no		
					dr	D.INGRAM	01/25/06	sheet 2 of	size
					engr	D.BRANN	01/25/06	10061262	A4
					chr	D.BRANN	01/25/06	type	
					appd	D.BRANN	01/25/06	CUSTOMER Drawing	
sheet index	revision sheet								

# Mouser Electronics

Authorized Distributor

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